

International Microsystems, Packaging, Assembly and Circuits Technology (IMPACT) Conference

In line with its very strong IC foundry industry for more than 30 years, Taiwan has also developed into a pivotal position in the world's IC packaging, testing and PCB arena. Considering the global number one revenue generated by Taiwan industries on packaging (44.8%), testing (60%) and PCBs (25%), the **International Microsystems, Packaging, Assembly and Circuits Technology (IMPACT)** conference will take place at Taipei International Convention Center Taiwan on October 1-3, 2007. Original and unpublished papers on all aspects of microsystems, packaging, assembly, and PCBs are solicited.

IMPACT Conference Keynote Speakers

Dr. Michael Pecht, University of Maryland, USA
Dr. C. P. Wong, Georgia Institute of Technology, USA
Dr. Kazuhiko Hashimoto, SONY, Japan
Dr. Dongkai Shanguan, Flextronics, Asia Pacific

Organized by ITRI, IEEE's CPMT-Taipei Chapter, IMAPS-Taiwan and TPCA, and with technical co-sponsorship by the CPMT Society, the **IMPACT** conference and TPCA Show 2007 is expecting to create Packaging and PCB – Taiwan to bring together scientists and engineers actively engaged in research and development on microsystems, IC packaging, assembly and PCBs to discuss current progress and emerging technologies in these fields.

IMPACT Conference: Mon.-Wed, Oct. 1-3, 2007
Taipei International Convention Center

AFEC Conference: Wed, Oct. 3, 2007
Taipei International Convention Center

Exhibition & TPCA Show: Wed.-Fri, Oct. 3-5, 2007
Taipei World Trade Center (Hall I & Hall III)

Visit the IMPACT Website:

impact.itri.org.tw

31st International Spring Seminar on Electronics Technology "Reliability and Life-time Prediction"

7-11 May, 2008
Budapest, Hungary

ISSE is the premier European forum for the exchange of information between young scientists from academic communities and electronic industries from around the world on topics related to their experimental and theoretical work in the very wide-spread field of microelectronics technology and electronics packaging. Based on a unique combination of oral and poster presentations as well as individual meetings, senior and junior researchers can come together to discuss scientific problems and organize international cooperation and student exchanges in a convenient atmosphere during three conference days. It is our pleasure to encourage you to participate in ISSE 2008.

the **International Academic Conference on Electronic Packaging Education and Training** will take place at the same venue on 7th May 2008. The aim of the Academic Conference is to catalyze education innovations by bringing together faculty from around the globe. For this purpose, academic people in the field of Electronic Packaging are invited from North America, Asia and Europe to exchange their knowledge and experience.

Topics of Interest:

- Reliability physics: analysis and life time-prediction in electronics;
- Non-destructive testing, picture acquisition methods;
- Nanotechnology, nanomaterials and nanoelectronics;
- Advanced packaging, new packages and materials, optoelectronics, optical interconnection technology;
- System on chip, system in package;
- Manufacturing processes, process simulation and optimization;
- Innovations in printed circuit board, thin film and thick film techniques;
- Education and information technology in electronics technology;
- System modeling, CAD/CAE in packaging;
- Bio-compatible electronics packaging, environmental, ecology, and toxicology issues in electronics technology

For more information on ISSE 2008, please visit:

www.isse-eu.net